

**TECENSTAR**

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# SPECIFICATION

## COG-T430MINI-18

- Preliminary Specification
- Final Specification



**TECENSTAR PHOTOELECTRIC  
TECHNOLOGY CO., LTD.**

**CUSTOMER:**

**Made By:**

**Checked By:**

**Approved By:**

**Quality:**

**Date:**

**Note:**

**Approved By:**

**Date:**

**Note:**



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# 1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	105.5*67.2*2.9	MM
ACTIVE SIZE (W*H)	95.04*53.86	MM
PIXEL PITCH (W*H)	0.198*0.198	MM
NUMBER OF DOTS	480*272	
DIVER IC	ILI6480BQ	
INTERFACE TYPE	24-BIT RGB	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	12	O'CLOCK
GRAY SCALE INVERSION DIRECTION	6	O'CLOCK
COLORS	16.7M	
BACKLIGHT TYPE	9-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

# 2. Mechanical Drawing

**Pinout Table:**

Pin Number	Function Description
1	Power for LED backlight driver
2	Power ground
3	Power for LED backlight driver
4	Power ground
5	Red data (USB)
6	Red data (USB)
7	Red data (USB)
8	Red data (USB)
9	Red data (USB)
10	Red data (USB)
11	Red data (USB)
12	Red data (USB)
13	Red data (USB)
14	Red data (USB)
15	Red data (USB)
16	Red data (USB)
17	Red data (USB)
18	Red data (USB)
19	Red data (USB)
20	Red data (USB)
21	Red data (USB)
22	Red data (USB)
23	Red data (USB)
24	Red data (USB)
25	Red data (USB)
26	Red data (USB)
27	Red data (USB)
28	Red data (USB)
29	Power ground
30	Power ground
31	Power ground
32	Power ground
33	Power ground
34	Power ground
35	Power ground
36	Power ground
37	Power ground
38	Power ground
39	Power ground
40	Power ground
41	Power ground
42	Power ground
43	Power ground
44	Power ground
45	Power ground
46	Power ground
47	Power ground
48	Power ground
49	Power ground
50	Power ground
51	Power ground
52	Power ground
53	Power ground
54	Power ground
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57	Power ground
58	Power ground
59	Power ground
60	Power ground
61	Power ground
62	Power ground
63	Power ground
64	Power ground
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66	Power ground
67	Power ground
68	Power ground
69	Power ground
70	Power ground
71	Power ground
72	Power ground
73	Power ground
74	Power ground
75	Power ground
76	Power ground
77	Power ground
78	Power ground
79	Power ground
80	Power ground
81	Power ground
82	Power ground
83	Power ground
84	Power ground
85	Power ground
86	Power ground
87	Power ground
88	Power ground
89	Power ground
90	Power ground
91	Power ground
92	Power ground
93	Power ground
94	Power ground
95	Power ground
96	Power ground
97	Power ground
98	Power ground
99	Power ground
100	Power ground

**Display Type:** TFT  
**Transmission:** TRANSMISSIVE POSITIVE  
**Optimum Viewing Direction:** 12 O'CLOCK  
**Upper Polarizer Type:** Anti-Glare  
**LCD Driver IC:** ILI6480B0  
**Operating Voltage:** VDD=3.3V  
**Operation Temperature:** -20°C TO 70°C  
**Storage Temperature:** -30°C TO 80°C  
**Interface:** 24bit-RGB  
**Backlight:** 9-LED WHITE 20MA/28.8V  
**Surface luminance:** 550cd/m<sup>2</sup>  
**White X/Y:** X: 0.31±0.02/Y: 0.35±0.02

**Dimensions:**  
 Top view: 105.50±0.2 (OUT LINE), 98.70±0.2 (OPEN), 95.04(A.A), 67.20±0.2 (OUT LINE), 44.01±0.5  
 Side view: 2.80±0.20, 0.3±0.03, 5.00±0.2, 20.50±0.1  
 Detail C: 5:1, 40, W=0.35, S=0.15, P=0.5, P0.5\*(40-1)=19.5±0.05, 20.5±0.1, 0.5, 0.198, 0.198, R C B R, R C B R

**Notes:**  
 1. Case Tolerance: ±0.2  
 2. ( ) Reference dimension.  
 3. Recommended Case Open Area Should Be Less Than Module VA  
 4. Recommended Case Open Area Should Be Less Than Module VA  
 5. PCB MUST BE COMPLIANT

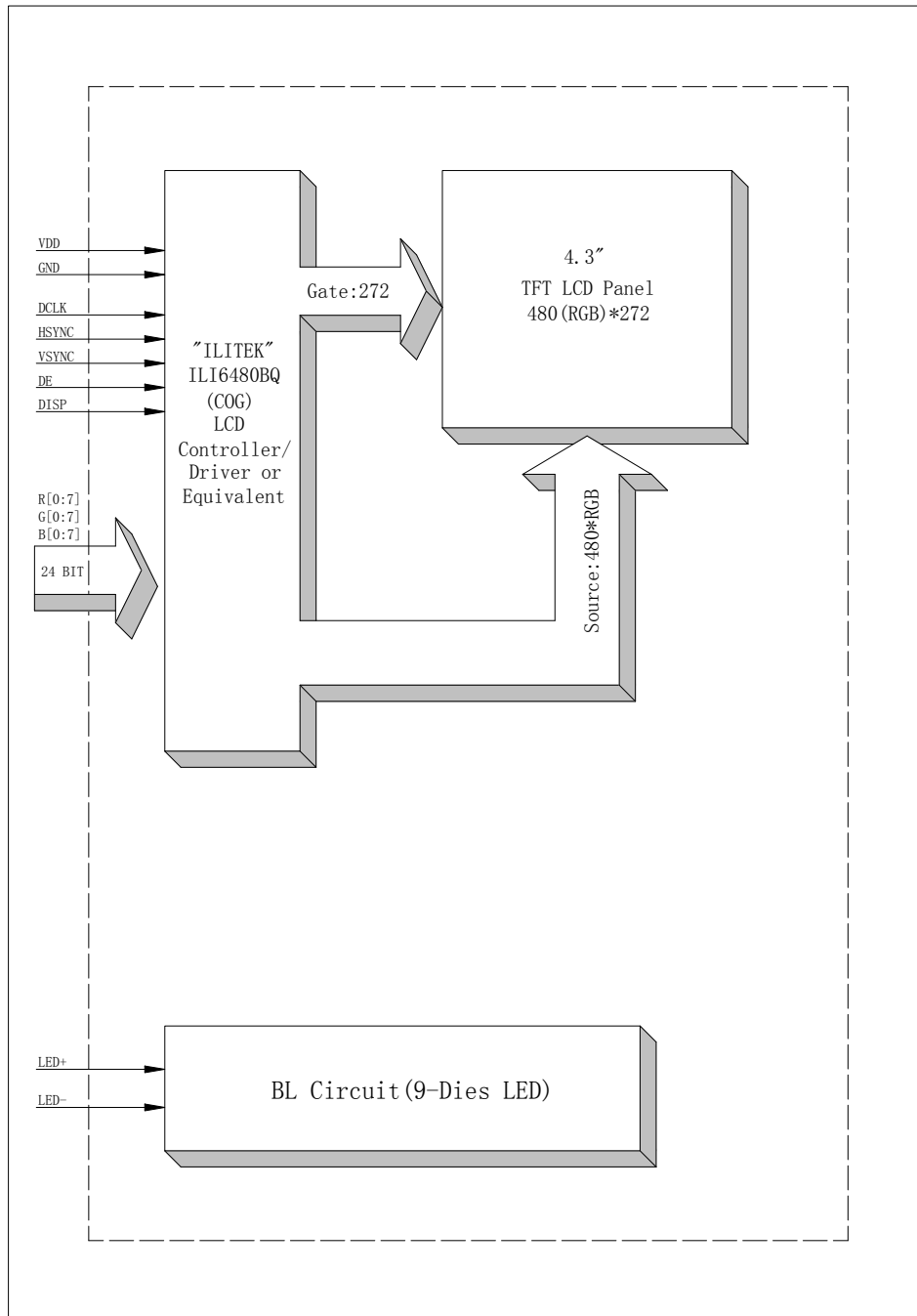
**Pinout Table (continued):**

Pin Number	Function Description
101	Power ground
102	Power ground
103	Power ground
104	Power ground
105	Power ground
106	Power ground
107	Power ground
108	Power ground
109	Power ground
110	Power ground
111	Power ground
112	Power ground
113	Power ground
114	Power ground
115	Power ground
116	Power ground
117	Power ground
118	Power ground
119	Power ground
120	Power ground
121	Power ground
122	Power ground
123	Power ground
124	Power ground
125	Power ground
126	Power ground
127	Power ground
128	Power ground
129	Power ground
130	Power ground
131	Power ground
132	Power ground
133	Power ground
134	Power ground
135	Power ground
136	Power ground
137	Power ground
138	Power ground
139	Power ground
140	Power ground
141	Power ground
142	Power ground
143	Power ground
144	Power ground
145	Power ground
146	Power ground
147	Power ground
148	Power ground
149	Power ground
150	Power ground

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### 3. Block Diagram



## 4. Interface Pin Function

Pin No.	Symbol	Description
1	LED-	Cathode of LED backlight
2	LED+	Anode of LED backlight
3	GND	Power ground
4	VDD	Power supply
5~12	R0~R7	8-bit digital Red data input,
13~20	G0~G7	8-bit digital Green data input,
21~28	B0~B7	8-bit digital Blue data input,
29	GND	Power ground
30	DCLK	Clock signal; latching data at the falling edge
31	DISP	Display control / standby mode selection. DISP = "Low" : Standby; DISP = "High" : Normal display(Default)
32	HSYNC	Horizontal sync signal; negative polarity
33	VSYNC	Vertical sync signal; negative polarity
34	DE	Data input enable. Active High to enable the data input.
35	NC	No connection.
36	GND	Power ground
37	NC	No connection.
38	NC	No connection.
39	NC	No connection.
40	NC	No connection.

## 5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VDD	-0.3	4.5	V
Supply voltage for logic	VDD	-0.3	4.5	V
Supply current (One LED)	I <sub>LED</sub>		30	mA
Operating temperature	T <sub>OP</sub>	-20	+70	°C
Storage temperature	T <sub>ST</sub>	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.



## 6. Electrical Characteristics

### 6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VDD	3.0	3.3	3.6	V	
Supply Voltage for Logic	VDD	3.0	3.3	3.6	V	
Input Voltage	V <sub>IL</sub>	GND	-	0.3VCC	V	
	V <sub>IH</sub>	0.7 VCC	-	VCC		
Input leakage Current	I <sub>LKG</sub>	-1		1	μA	

### 6.2 Backlight Driving Conditions

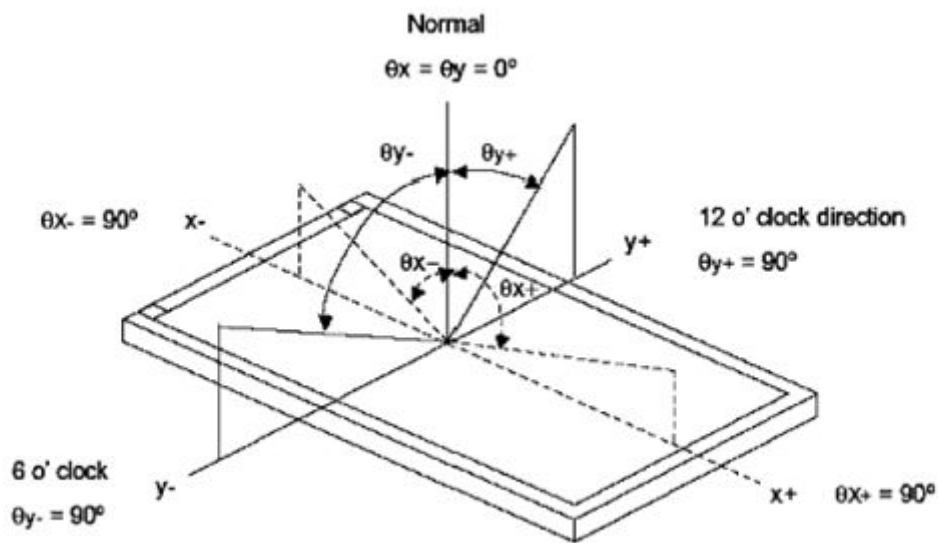
Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V <sub>F</sub>	-	28.8	-	V	I <sub>L</sub> =20mA
Current for LED Backlight	I <sub>L</sub>		20		mA	
Power Consumption	P		0.576		W	
LED Life Time		30,000			Hr	Note

**Note:** Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

## 7. Optical Characteristics

ITEM	SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
			MIN	TYP.	MAX		
Luminance	L	$I_L = 20\text{mA}$		550		$\text{Cd/m}^2$	
Contrast Ratio	CR	$\theta = 0^\circ$	400	500			
Response Time	$T_{\text{ON}}$	$25^\circ\text{C}$		10	20	ms	
	$T_{\text{OFF}}$			15	30		
CIE Color Coordinate	Red	$X_R$	Viewing normal angle				
		$Y_R$					
	Green	$X_G$					
		$Y_G$					
	Blue	$X_B$					
		$Y_B$					
	White	$X_W$			0.31		
		$Y_W$			0.35		
Viewing Angle	Hor.	$\theta_{X+}$	$CR \geq 10$	60	70	Degree	
		$\theta_{X-}$		60	70		
	Ver.	$\theta_{Y+}$		40	50		
		$\theta_{Y-}$		60	70		
Uniformity	Un			80		%	

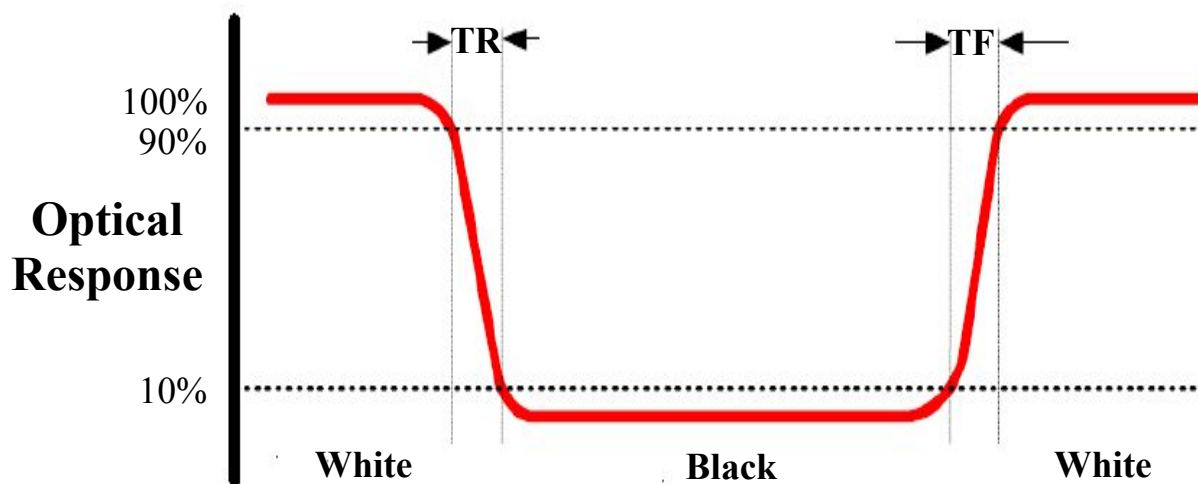
**Note 1: Definition of Viewing Angle  $\theta_x$  and  $\theta_y$ :**



**Note 2: Definition of contrast ratio CR:**

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

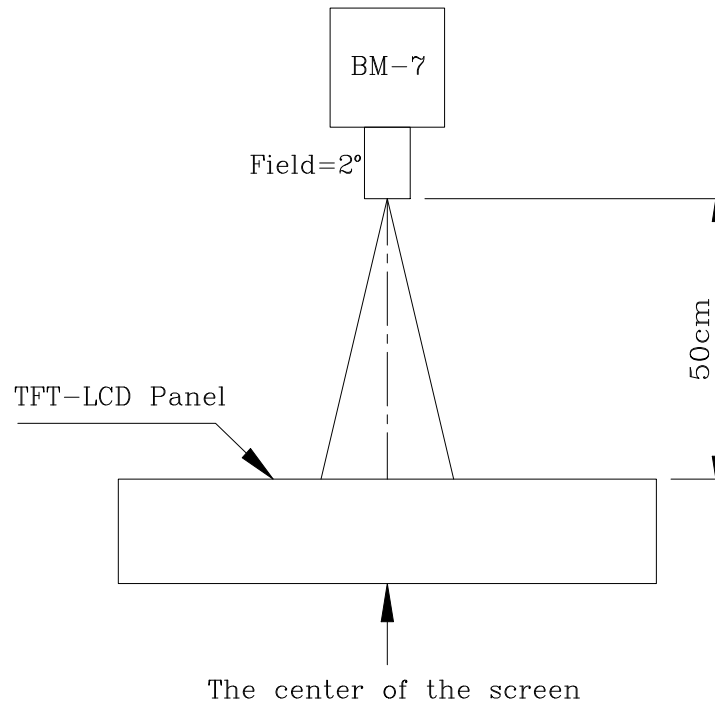
**Note 3: Definition of Response Time ( $T_r, T_f$ )**



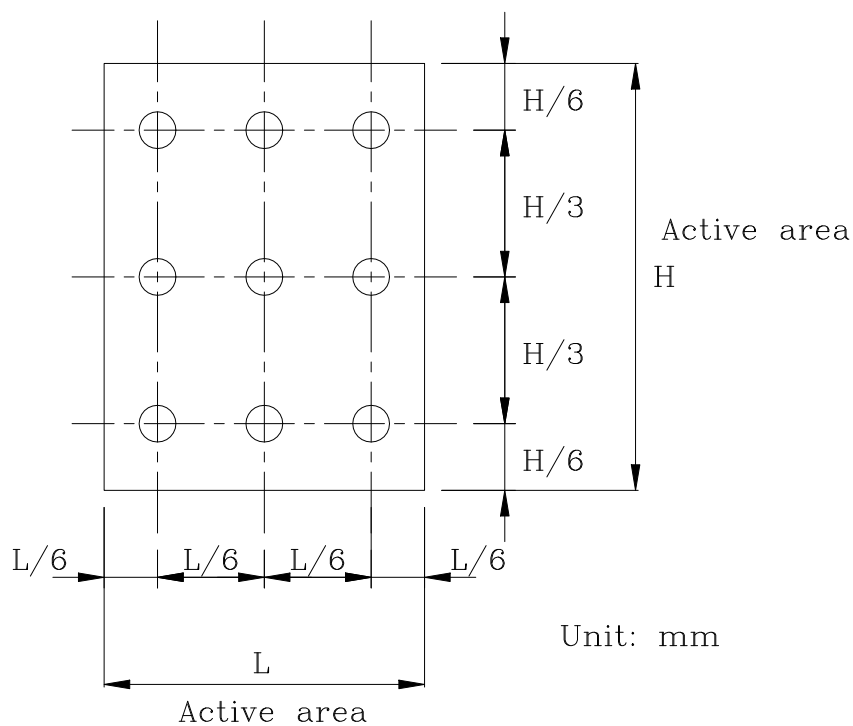
## Note 4: Definition of Luminance

### ①The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)

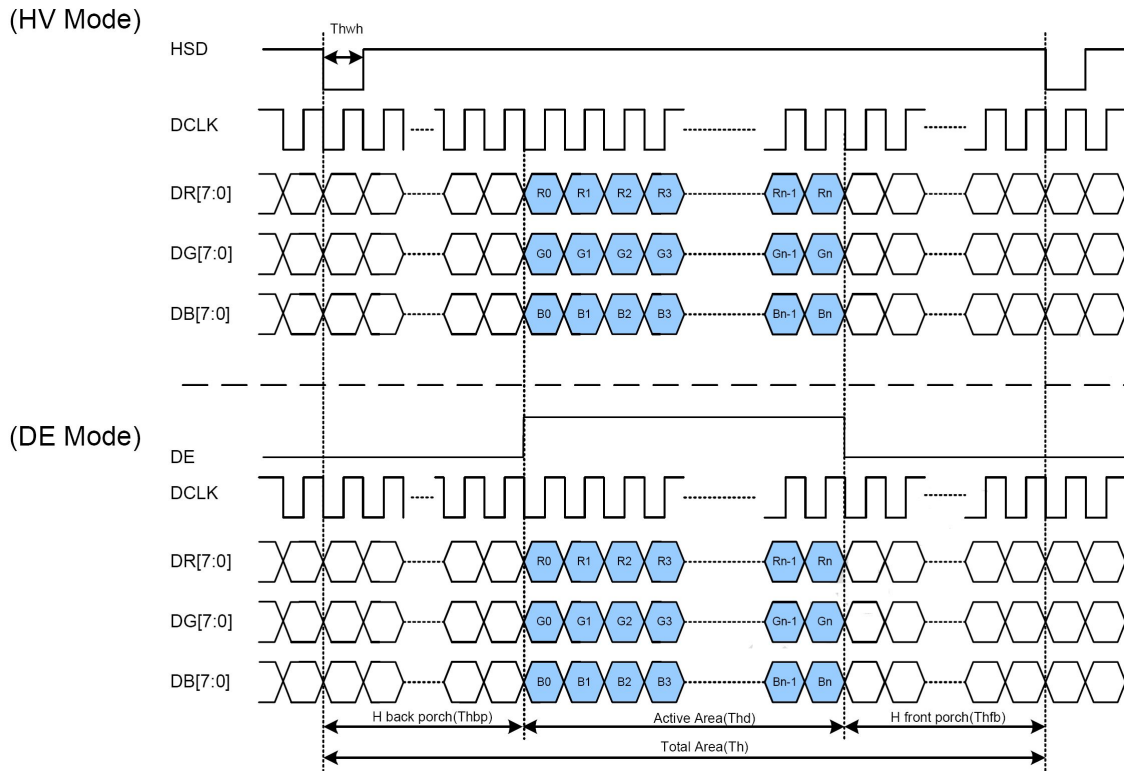


### ②The Brightness Test Point Setup



# 8. Timing Characteristics

## 8.1 Parallel RGB Mode Timing Diagram

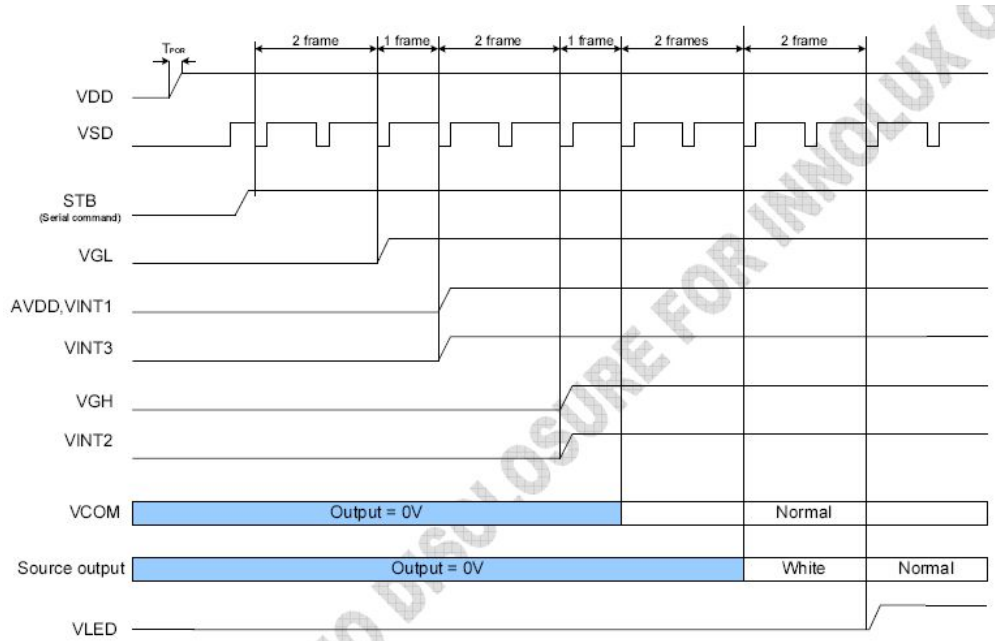


## 8.2 Parallel RGB Timing Table

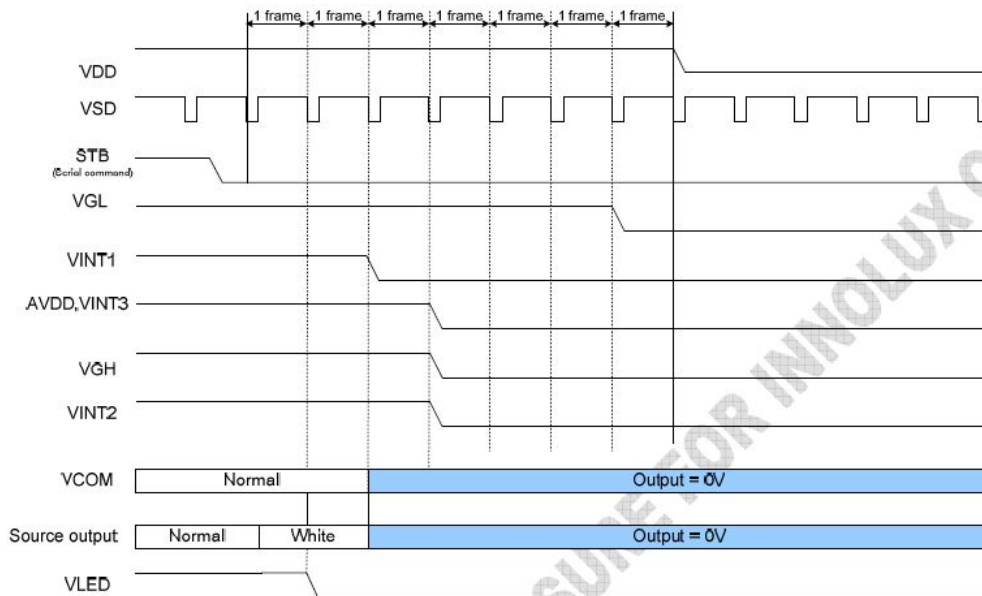
Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
DCLK frequency	fclk	5	9	12	MHz
VSD period time	$T_v$	277	288	400	H
VSD display area	$T_{vd}$	272			H
VSD back porch	$T_{vb}$	3	8	31	H
VSD front porch	$T_{vfp}$	2	8	97	H
HSD period time	$T_h$	520	525	800	DCLK
HSD display area	$T_{hd}$	480			DCLK
HSD back porch	$T_{hbp}$	36	40	255	DCLK
HSD front porch	$T_{hfp}$	4	5	65	DCLK

## 8.3 Power ON/OFF Sequence

### Power on



### Power off



## 9. Standard Specification for Reliability

### 9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

\*Sample size for each test item is 3~5pcs

## 9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

## 9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ( $25\pm 5^{\circ}\text{C}$ ), normal humidity ( $50\pm 10\%$ RH), and in area not exposed to direct sun light.
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## 10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

### 10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

### 10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single time.
- The defects classify of AQL as following:  
Major defect: AQL = 0.65  
Minor defect: AQL = 2.5  
Total defects: AQL = 2.5

### 10.3 Non-conforming Analysis & Deal with Manners

#### 10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

#### 10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

## 10.4 Agreement items

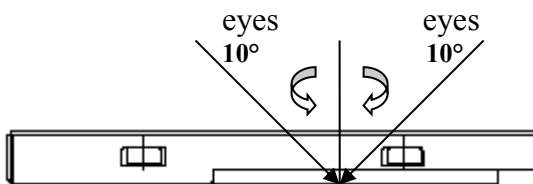
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

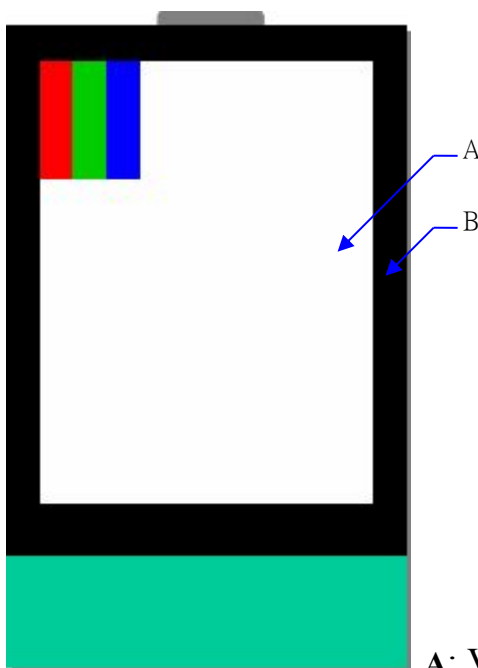
## 10.5 Standard of the Product Appearance Test

### 10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



- Definition of area:

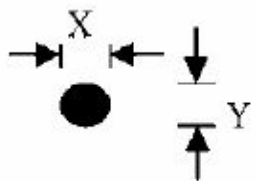
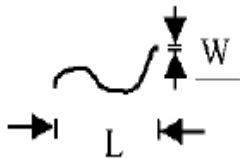


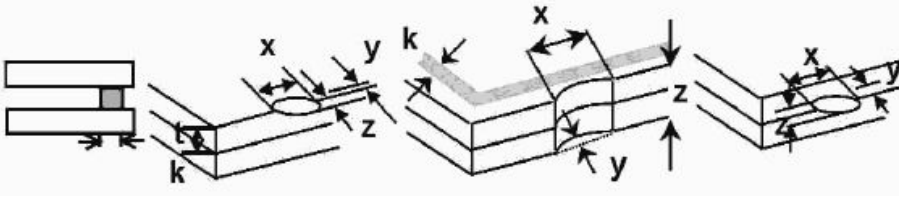
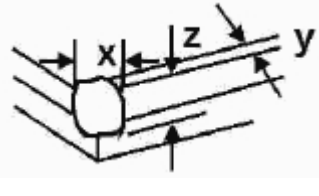
A: Viewing area B: Outside viewing area

### 10.5.2 Basic principle

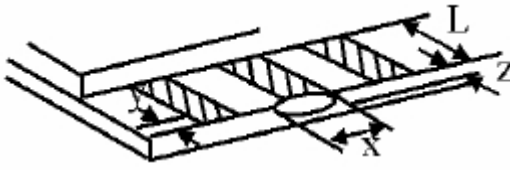
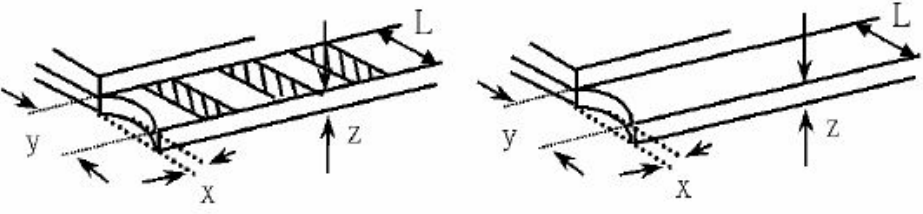
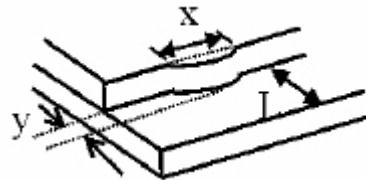
- When the standard cannot be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

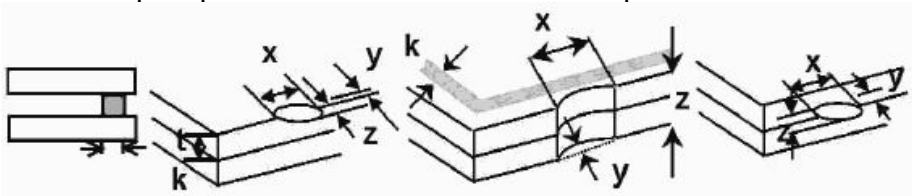
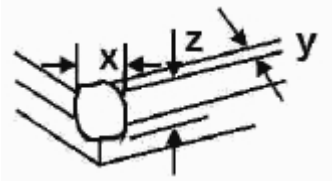
## 10.6 Inspection Specification

NO.	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$ , no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	2.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="821 1120 1356 1377"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.10</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.10 &lt; \Phi \leq 0.20</math></td> <td>2</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.25</math></td> <td>2</td> </tr> <tr> <td><math>0.25 &lt; \Phi \leq 0.30</math></td> <td>1</td> </tr> <tr> <td><math>0.30 &lt; \Phi</math></td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	2.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="726 1523 1356 1803"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td><math>W \leq 0.02</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>L \leq 3.0</math></td> <td><math>0.02 &lt; W \leq 0.05</math></td> <td rowspan="2">2</td> </tr> <tr> <td><math>L \leq 2.5</math></td> <td><math>0.03 &lt; W \leq 0.08</math></td> </tr> <tr> <td>---</td> <td><math>0.08 &lt; W</math></td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	2.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

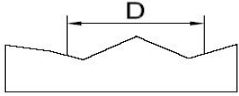
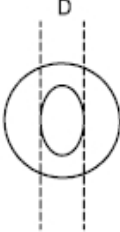
NO.	Item	Criterion		AQL								
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size $\Phi$ (mm)	Acceptable Q'ty	2.5							
			$\Phi \leq 0.20$	Accept no dense								
			$0.20 < \Phi \leq 0.50$	3								
			$0.50 < \Phi \leq 1.00$	2								
			1.00 < $\Phi$	0								
			Total Q'ty	3								
05	Scratches	Follow NO.3 -2 Line Type.										
06	Chipped glass	Symbols: x: Chip length    y: Chip width    z: Chip thickness k: Seal width    t: Glass thickness    a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:		2.5								
												
		z: Chip thickness	y: Chip width		x: Chip length							
		$Z \leq 1/2t$	Not over viewing area		$x \leq 1/8a$							
		$1/2t < z \leq 2t$	Not exceed 1/3k		$x \leq 1/8a$							
⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip		6.1.2 Corner crack:										
		<table border="1"> <thead> <tr> <th data-bbox="432 1630 708 1673">z: Chip thickness</th> <th data-bbox="713 1630 1023 1673">y: Chip width</th> <th data-bbox="1027 1630 1265 1673">x: Chip length</th> </tr> </thead> <tbody> <tr> <td data-bbox="432 1680 708 1740"><math>Z \leq 1/2t</math></td> <td data-bbox="713 1680 1023 1740">Not over viewing area</td> <td data-bbox="1027 1680 1265 1740"><math>x \leq 1/8a</math></td> </tr> <tr> <td data-bbox="432 1747 708 1807"><math>1/2t &lt; z \leq 2t</math></td> <td data-bbox="713 1747 1023 1807">Not exceed 1/3k</td> <td data-bbox="1027 1747 1265 1807"><math>x \leq 1/8a</math></td> </tr> </tbody> </table>		z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$
z: Chip thickness	y: Chip width	x: Chip length										
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$										
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$										
⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip												

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\cong$ 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\cong$ 1/2 alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO.	Item	Criterion	AQL						
07	Glass crack	<p>Symbols:            x: Chip length    y: Chip width    z: Chip thickness            k: Seal width    t: Glass thickness    a: LCD side length            L: Electrode pad length</p> <p>7.2 Protrusion over terminal:            7.2.1 Chip on electrode pad:</p>  <table border="1" data-bbox="558 761 1236 907"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq 0.5\text{mm}</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	2.5
		y: Chip width	x: Chip length	z: Chip thickness					
		$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$					
<p>7.2.2            Non-conductive portion:</p>  <table border="1" data-bbox="558 1276 1236 1422"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td><math>y \leq L</math></td> <td><math>x \leq 1/8a</math></td> <td><math>0 &lt; z \leq t</math></td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$			
y: Chip width	x: Chip length	z: Chip thickness							
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$							
<p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.            ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>7.2.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="885 1747 1324 1892"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td><math>y \leq 1/3L</math></td> <td><math>X \leq a</math></td> </tr> </table>	y: width	x: length	$y \leq 1/3L$	$X \leq a$					
y: width	x: length								
$y \leq 1/3L$	$X \leq a$								

NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	<p>Symbols:            x: Chip length    y: Chip width    z: Chip thickness            k: Seal width    t: Touch Panel Total thickness    a: LCD side length            L: Electrode pad length</p> <p>14.1 General glass chip:            14.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="451 763 1270 981"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>Z \leq t</math></td> <td><math>\cong 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm            ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>14.1.2 Corner crack:</p>  <table border="1" data-bbox="451 1357 1270 1574"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td><math>z \leq t</math></td> <td><math>\cong 1/2 k</math> and not over viewing area</td> <td><math>x \leq 1/8a</math></td> </tr> </table> <p>⊙ Unit: mm            ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\cong 1/2 k$ and not over viewing area	$x \leq 1/8a$													



NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table border="1" data-bbox="459 349 987 555"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.2</math></td> <td>Accept no dense</td> </tr> <tr> <td><math>0.2 &lt; D \leq 0.4</math></td> <td>5</td> </tr> <tr> <td><math>0.4 &lt; D \leq 0.5</math></td> <td>2</td> </tr> <tr> <td><math>0.5 &lt; D</math></td> <td>0</td> </tr> </tbody> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion ( $\leq 2.5\%$ ), it is acceptable.	2.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
18	LCD Ripple	Touch the touch panel, cannot see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
19	General appearance	<p>19.1 Pin type must match type in specification sheet.</p> <p>19.2 LCD pin loose or missing pins.</p> <p>19.3 Product packaging must the same as specified on packaging specification sheet.</p> <p>19.4 Product dimension and structure must conform to product specification sheet.</p>	<p>0.65</p> <p>0.65</p> <p>0.65</p> <p>0.65</p>										

## 11. Handling Precaution

### 11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

### 11.2 Storage

- Store it in an ambient temperature of  $25\pm 10^{\circ}\text{C}$ , and in a relative humidity of  $50\pm 10\%\text{RH}$ . Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

### 11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than  $280\pm 10^{\circ}\text{C}$  and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

## 12. Packing Method

----TBD